



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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LB W5SM

Golden DRAGON®



Applications

- Transportation, Plane, Ship

Features:

- Package: white SMD package, colorless clear silicone resin
- Chip technology: ThinGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color: $\lambda_{\text{dom}} = 467 \text{ nm}$ (● blue)
- Corrosion Robustness Class: 3B
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

Ordering Information

Type	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ Φ_V	Ordering Code
LB W5SM-FZHX-35	15 ... 33 lm	Q65110A9221

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	125 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	125 °C
Junction Temperature	T_j	max.	135 °C
Junction Temperature for short time applications*	T_j	max.	175 °C
Forward current $T_s = 25\text{ °C}$	I_F	min.	100 mA
		max.	1000 mA
Surge Current $t \leq 10\ \mu\text{s}; D = 0.005; T_s = 25\text{ °C}$	I_{FS}	max.	2500 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}		8kV
Reverse current ²⁾	I_R	max.	200 mA

*The median lifetime (L70/B50) for $T_j = 175\text{ °C}$ is 100h.

Characteristics

$I_F = 350 \text{ mA}$; $T_s = 25 \text{ °C}$

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	465 nm
Dominant Wavelength ³⁾ $I_F = 350 \text{ mA}$	λ_{dom}	min.	464 nm
		typ.	467 nm
		max.	476 nm
Spectral Bandwidth at 50% $I_{\text{rel,max}}$	$\Delta\lambda$	typ.	25 nm
Viewing angle at 50 % I_V	2ϕ	typ.	120 °
Forward Voltage ⁴⁾ $I_F = 350 \text{ mA}$	V_F	min.	2.70 V
		typ.	3.20 V
		max.	3.70 V
Reverse voltage (ESD device)	$V_{\text{RES D}}$	min.	45 V
Reverse voltage ²⁾ $I_R = 20 \text{ mA}$	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint ⁵⁾	$R_{\text{thJS real}}$	typ.	5 K / W
		max.	6.4 K / W

Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ max. Φ_V	Luminous Intensity ⁶⁾ $I_F = 350 \text{ mA}$ typ. I_V
FZ	15 lm	18 lm	05 cd
GX	18 lm	21 lm	06 cd
GY	21 lm	24 lm	07 cd
GZ	24 lm	28 lm	09 cd
HX	28 lm	33 lm	10 cd

Wavelength Groups

Group	Dominant Wavelength ³⁾ $I_F = 350 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ³⁾ $I_F = 350 \text{ mA}$ max. λ_{dom}
3	464 nm	468 nm
4	468 nm	472 nm
5	472 nm	476 nm

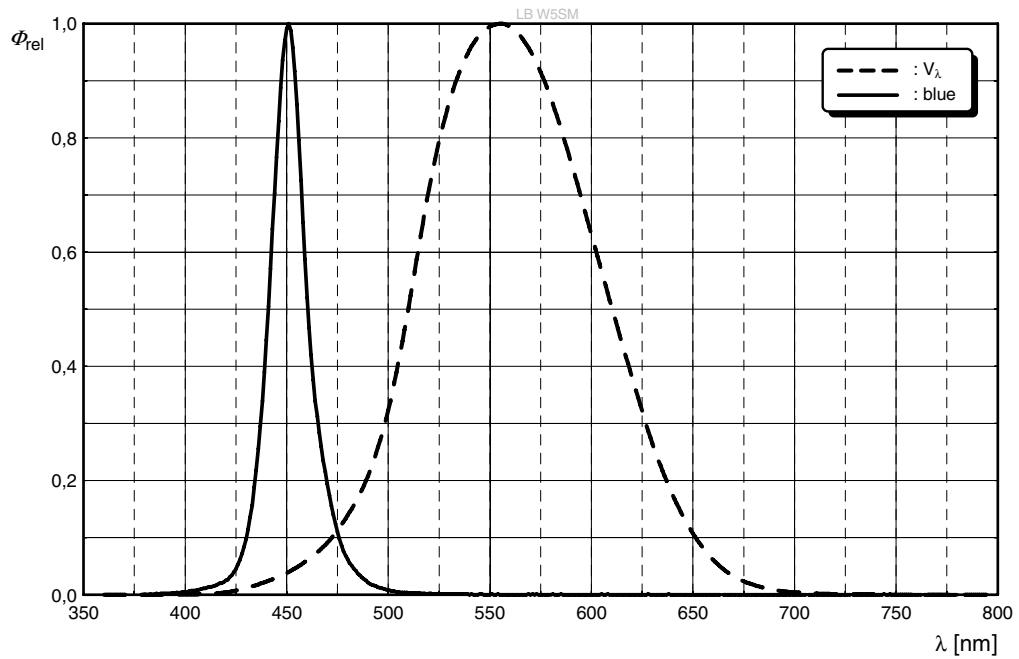
Group Name on Label

Example: FZ-3

Brightness	Wavelength
FZ	3

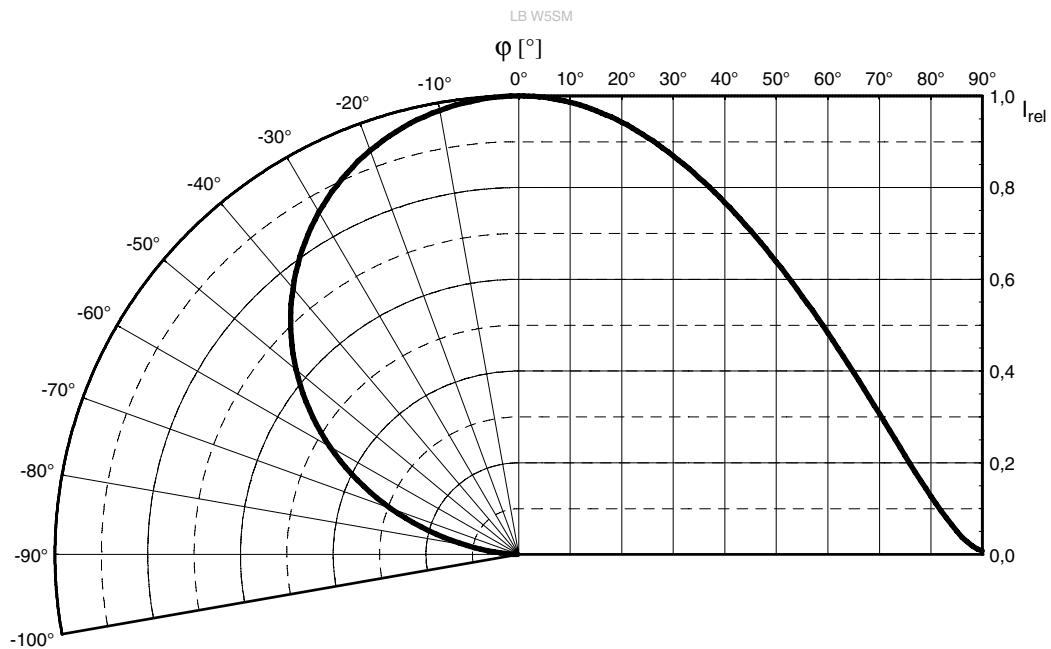
Relative Spectral Emission ⁶⁾

$I_{rel} = f(\lambda); I_F = 350 \text{ mA}; T_S = 25 \text{ }^\circ\text{C}$



Radiation Characteristics ⁶⁾

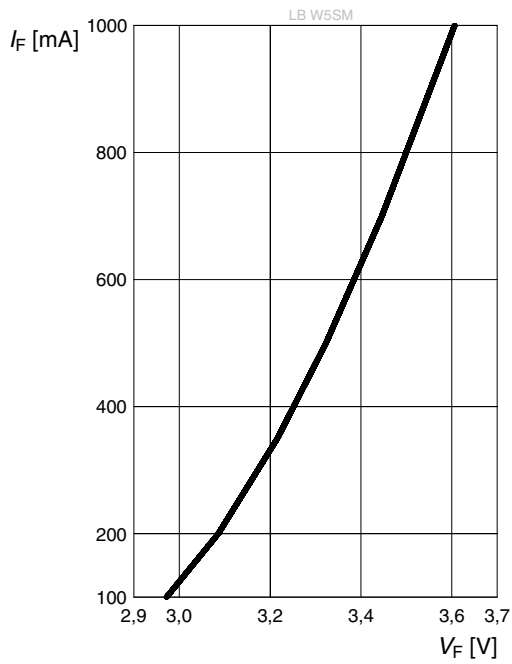
$I_{rel} = f(\phi); T_S = 25 \text{ }^\circ\text{C}$



Not for new design

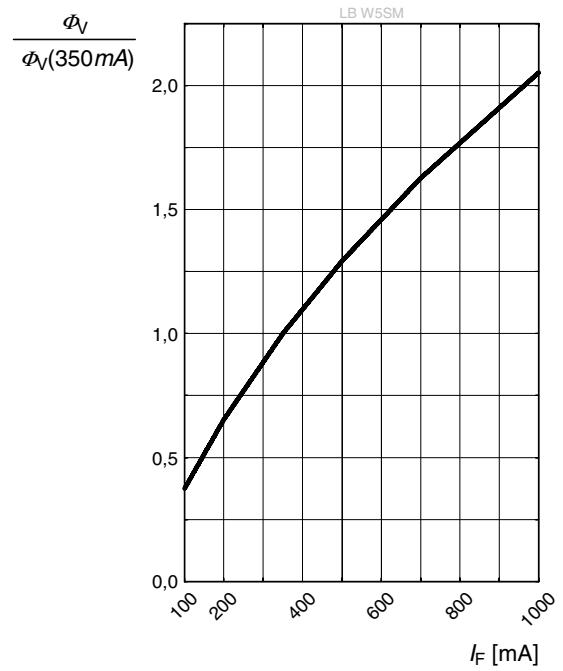
Forward current ^{6), 7)}

$I_F = f(V_F); T_S = 25\text{ °C}$



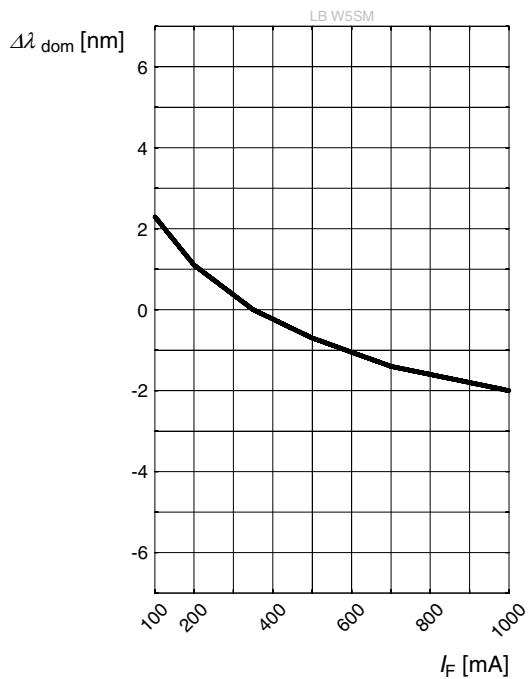
Relative Luminous Flux ^{6), 7)}

$\Phi_V/\Phi_V(350\text{ mA}) = f(I_F); T_S = 25\text{ °C}$



Dominant Wavelength ⁶⁾

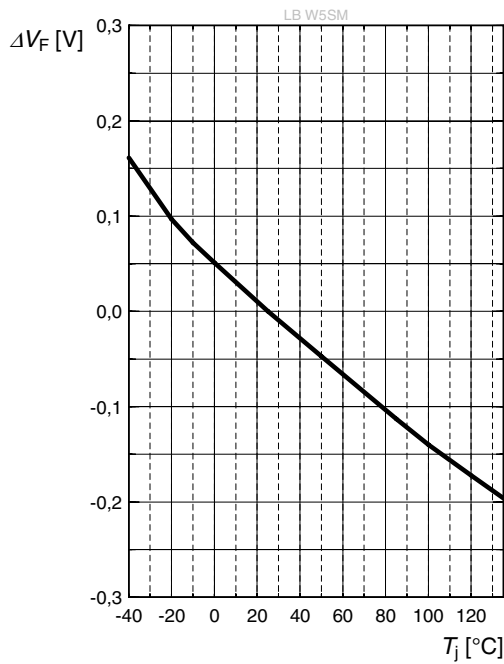
$\Delta\lambda_{\text{dom}} = f(I_F); T_S = 25\text{ °C}$



Not for new design

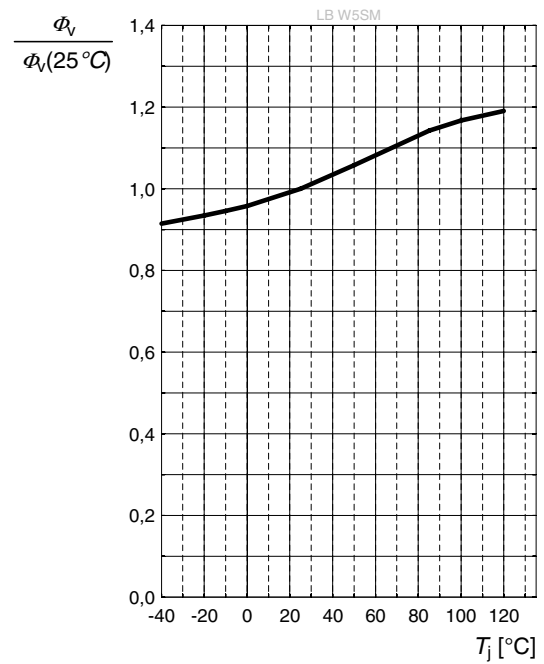
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(25\text{ °C}) = f(T_j); I_F = 350\text{ mA}$$



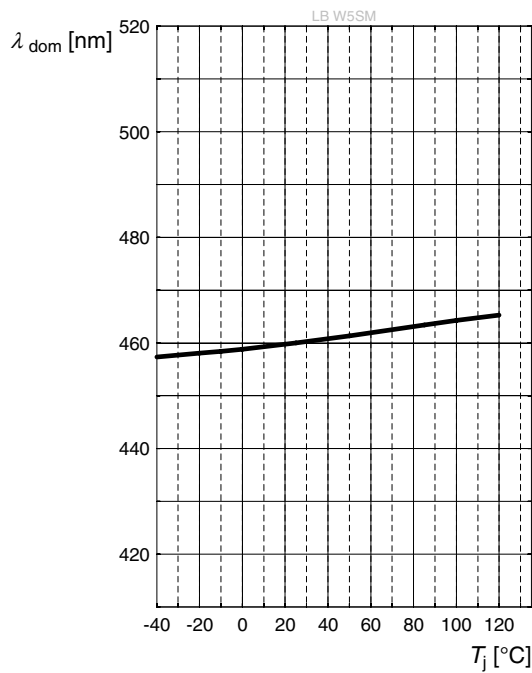
Relative Luminous Flux ⁶⁾

$$\Phi_V / \Phi_V(25\text{ °C}) = f(T_j); I_F = 350\text{ mA}$$



Dominant Wavelength ⁶⁾

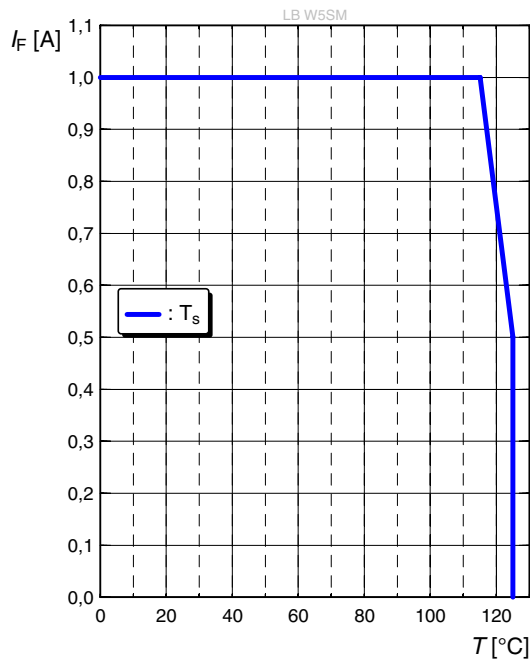
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}}(25\text{ °C}) = f(T_j); I_F = 350\text{ mA}$$



Not for new design

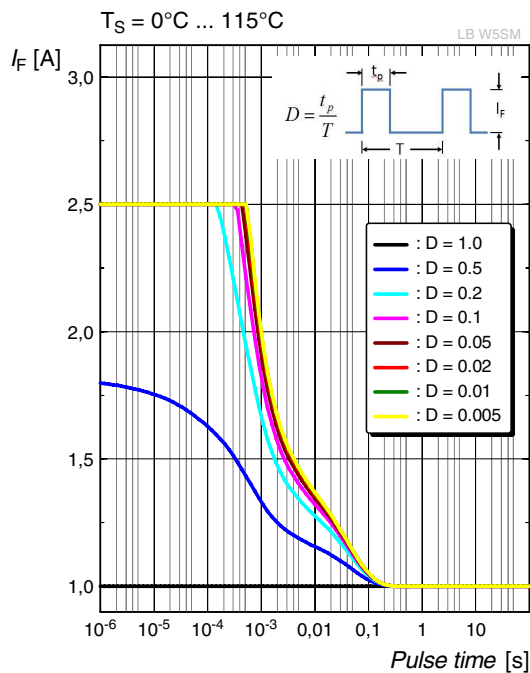
Max. Permissible Forward Current

$I_F = f(T)$



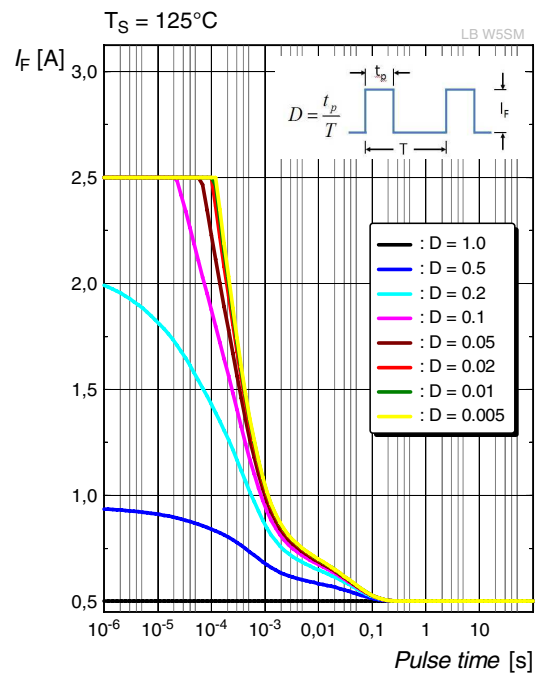
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle



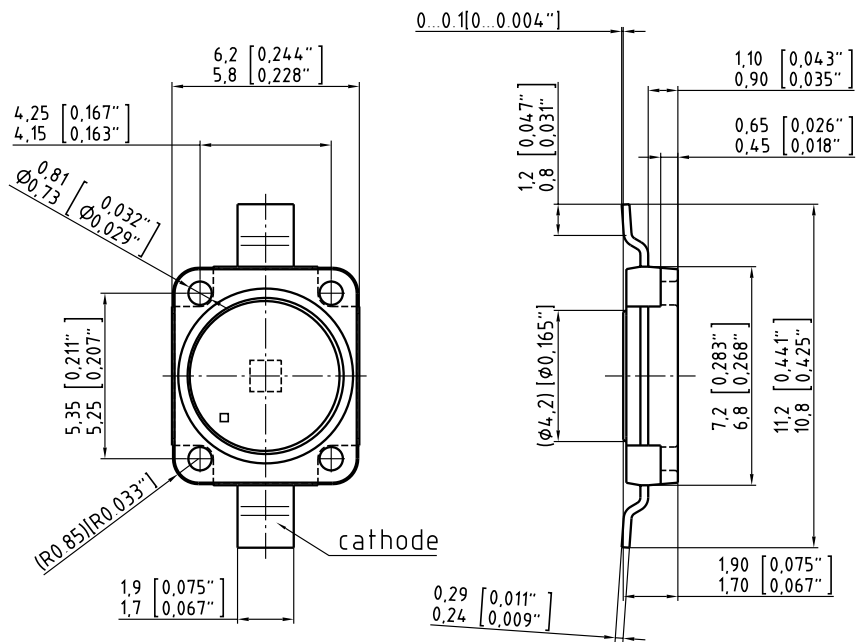
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle



Not for new design

Dimensional Drawing ⁸⁾



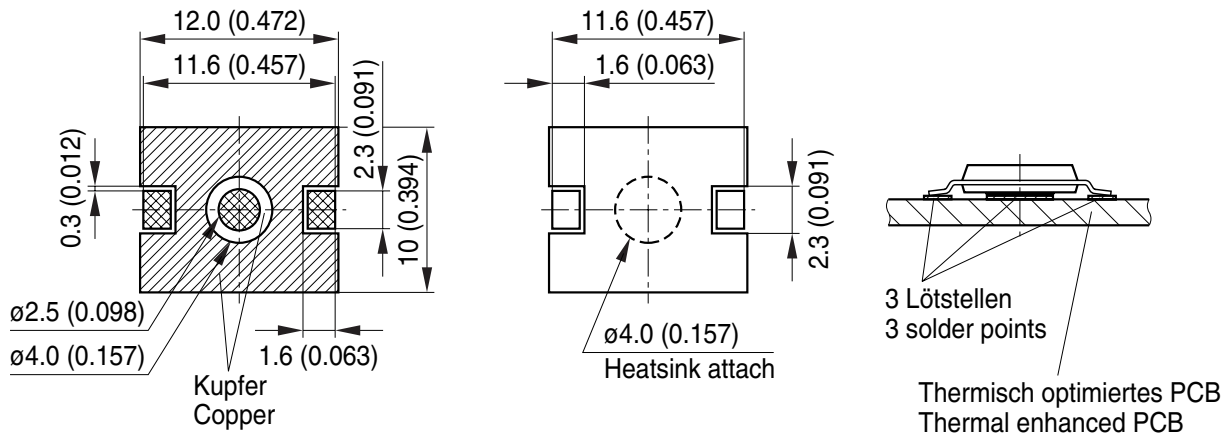
C63062-A3904-A1..-05




Approximate Weight: 218.0 mg

Corrosion test: Class: 3B
 Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC 60068-2-43)

ESD advice: LED is protected by ESD device which is connected in paralell to LED-Chip.

Recommended Solder Pad ⁸⁾



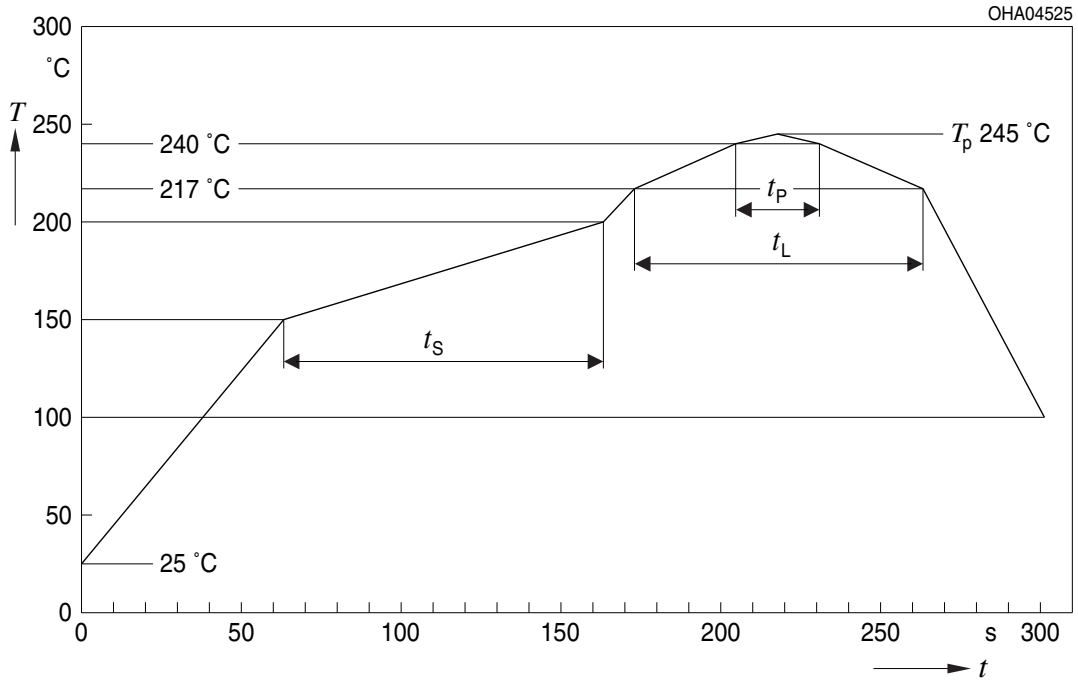
-  Lötstopplack
Solder resist
-  Lötpasten Schablone
Solder paste stencil
-  Bare Copper
Freies Kupfer

OHAY0681

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020D.01

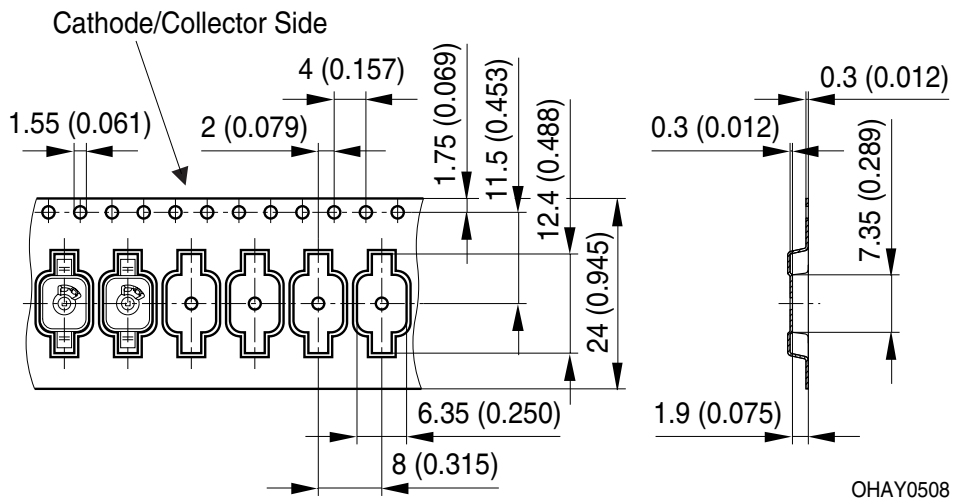


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

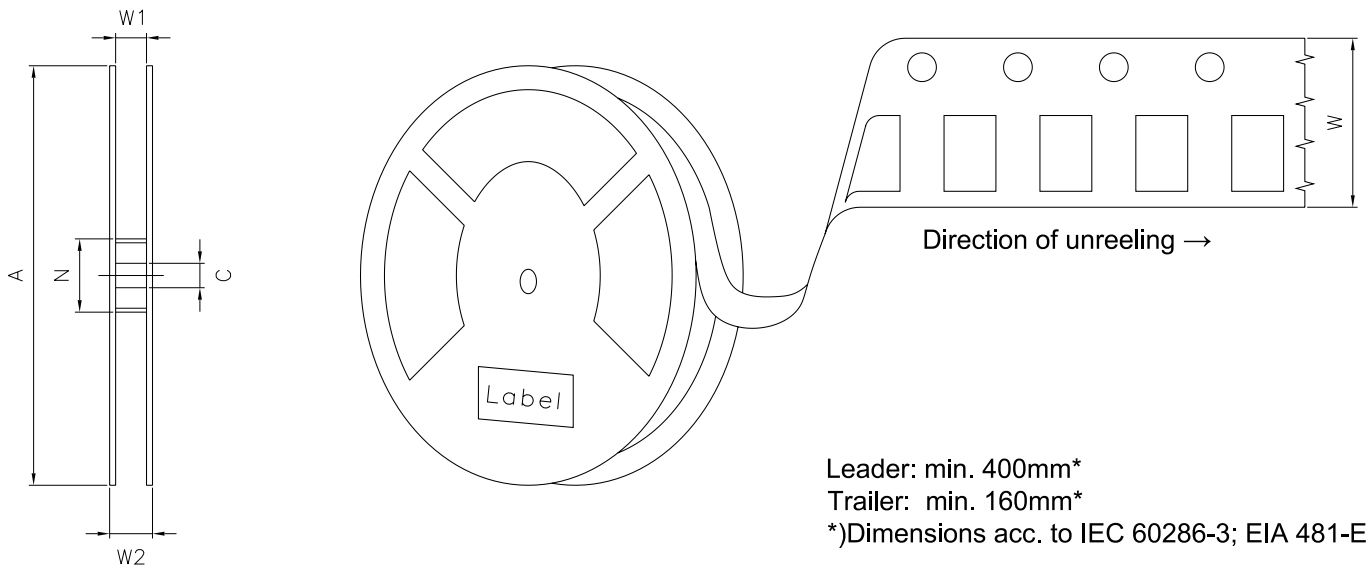
All temperatures refer to the center of the package, measured on the top of the component
 *) slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Not for new design

Taping ⁸⁾



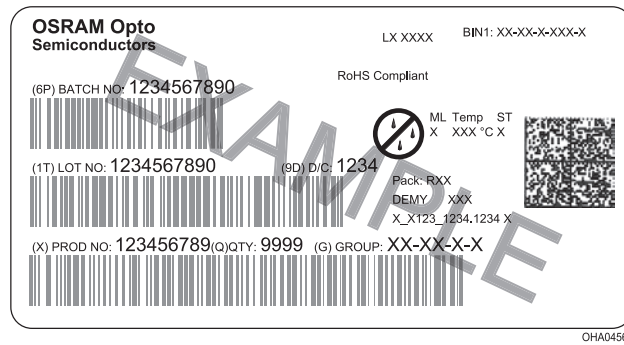
Tape and Reel ⁹⁾



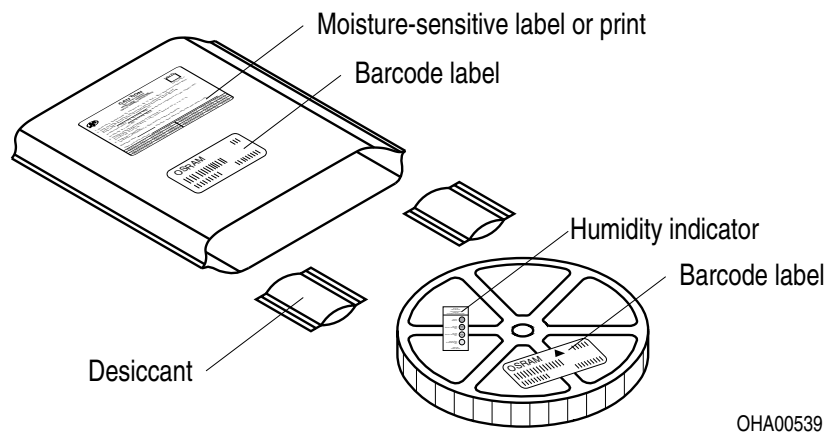
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2max}	Pieces per PU
180 mm	24 + 0.3 / - 0.1	60/100	24.4 + 2	30.4	800

Barcode-Product-Label (BPL)

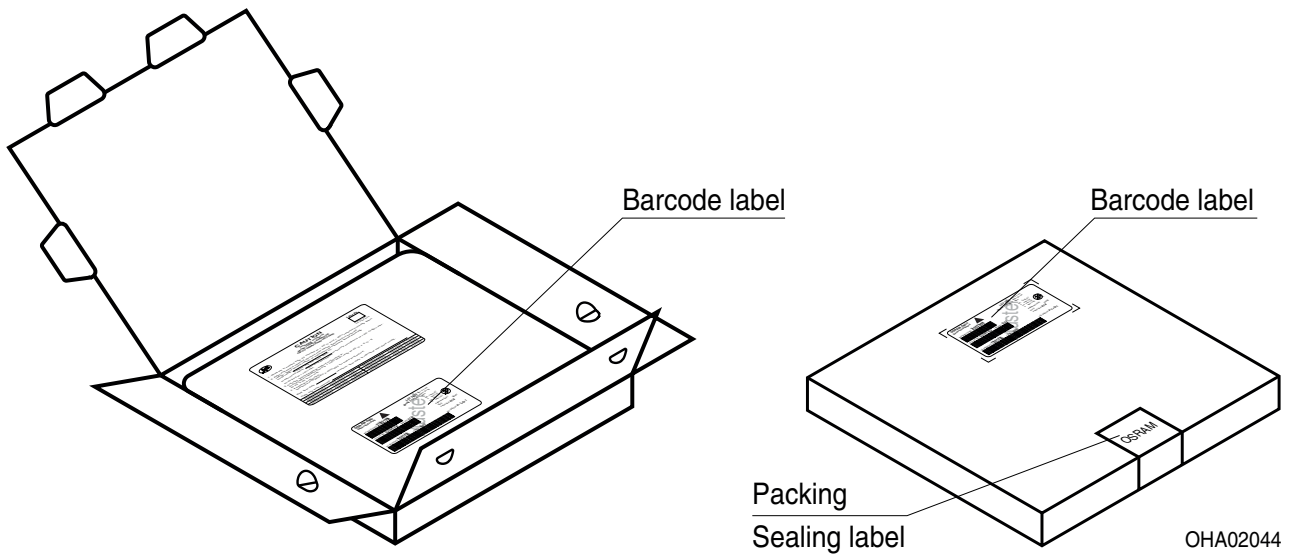


Dry Packing Process and Materials ⁸⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

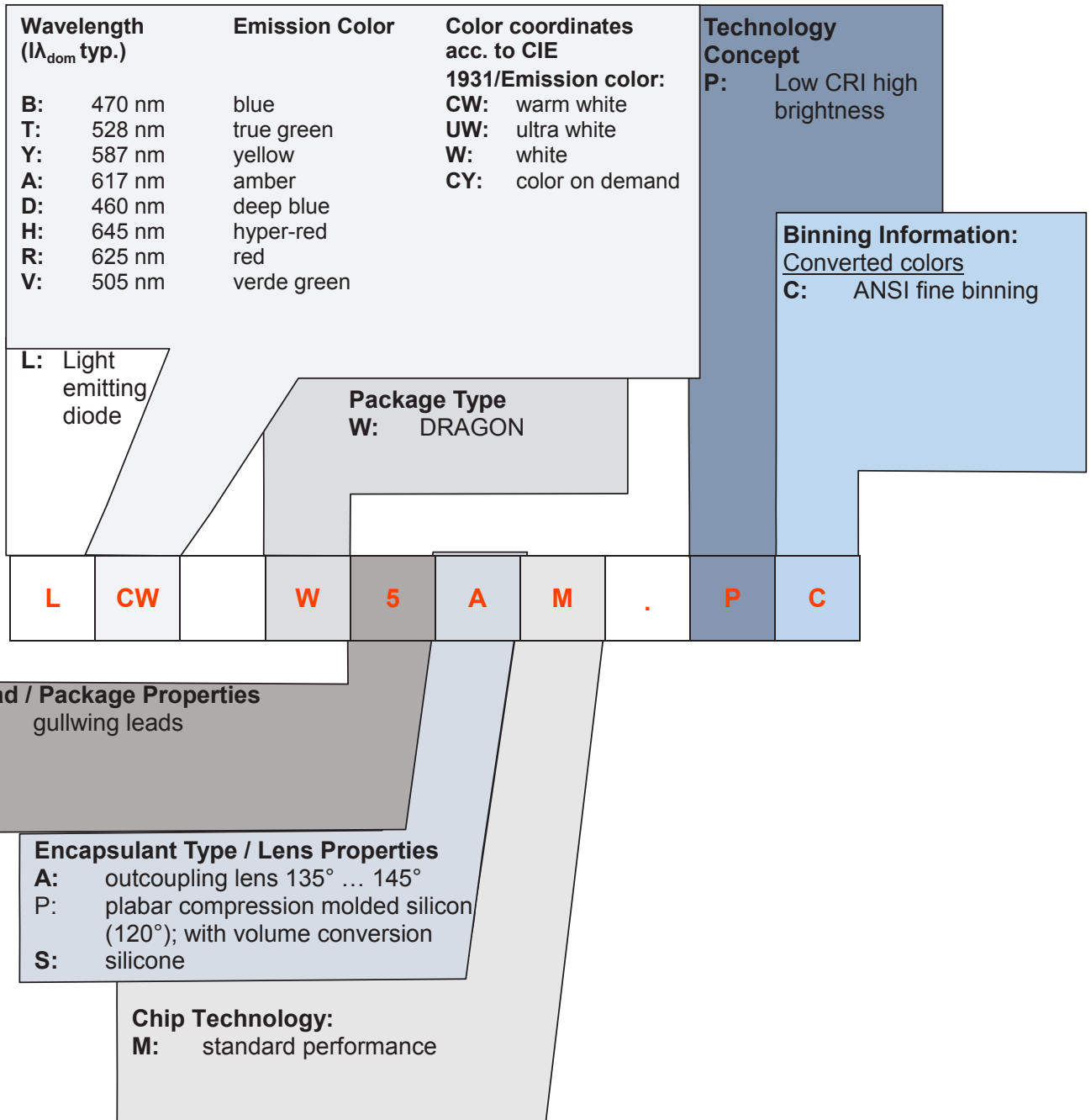
Transportation Packing and Materials ⁸⁾



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	42 ± 5 mm

Type Designation System



Not for new design

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. As is also true when viewing other bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes

Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ± 0.5 nm and an expanded uncertainty of ± 1 nm (acc. to GUM with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single LEDs within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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